

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2623715

SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>CHIN-SHENG CHEN</td> <td>10/30/2013</td> </tr> <tr> <td>TSUN-YU YANG</td> <td>10/30/2013</td> </tr> <tr> <td>WEI-YI HU</td> <td>10/30/2013</td> </tr> <tr> <td>JUI-FENG KUAN</td> <td>10/29/2013</td> </tr> <tr> <td>CHING-SHUN YANG</td> <td>10/29/2013</td> </tr> <tr> <td>YI-KAN CHENG</td> <td>11/04/2013</td> </tr> </tbody> </table>		Name	Execution Date	CHIN-SHENG CHEN	10/30/2013	TSUN-YU YANG	10/30/2013	WEI-YI HU	10/30/2013	JUI-FENG KUAN	10/29/2013	CHING-SHUN YANG	10/29/2013	YI-KAN CHENG	11/04/2013
Name	Execution Date														
CHIN-SHENG CHEN	10/30/2013														
TSUN-YU YANG	10/30/2013														
WEI-YI HU	10/30/2013														
JUI-FENG KUAN	10/29/2013														
CHING-SHUN YANG	10/29/2013														
YI-KAN CHENG	11/04/2013														
RECEIVING PARTY DATA															
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.														
Street Address:	NO. 8, LI-HSIN RD. VI														
Internal Address:	HSINCHU SCIENCE PARK														
City:	HSINCHU														
State/Country:	TAIWAN														
Postal Code:	300														
PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14086127</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14086127										
Property Type	Number														
Application Number:	14086127														
CORRESPONDENCE DATA															
Fax Number:															
Phone:	7036841111														
Email:	tsmc@ipfirm.com														
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>															
Correspondent Name:	LOWE HAUPTMAN & HAM, LLP (TSMC)														
Address Line 1:	2318 MILL ROAD														
Address Line 2:	SUITE 1400														
Address Line 4:	ALEXANDRIA, VIRGINIA 22314														
ATTORNEY DOCKET NUMBER:	T5057-967														

CH \$40.00 14086127

NAME OF SUBMITTER:	RANDY A. NORANBROCK
Signature:	/Randy A. Noranbrock/
Date:	11/21/2013
Total Attachments: 2 source=EfiledAssign#page1.tif source=EfiledAssign#page2.tif	

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Chin-Sheng CHEN
- 2) Tsun-Yu YANG
- 3) Wei-Yi HU
- 4) Jui-Feng KUAN
- 5) Ching-Shun YANG
- 6) Yi-Kan CHENG

who has made a certain new and useful invention, hereby sells, assigns and transfers unto TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

METHOD OF DESIGNING FIN FIELD EFFECT TRANSISTOR (FINFET)-BASED CIRCUIT AND SYSTEM FOR IMPLEMENTING THE SAME

(a) for which an application for United States Letters Patent was filed on November 21, 2013, and identified by United States Patent Application No. 14/086,127; or

(b) for which an application for United States Letters Patent was executed on _____.

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Chin Sheng Chen
Name: Chin-Sheng CHEN

10/30/2013
Date:

2) Tsun-Yu Yang
Name: Tsun-Yu YANG

10/30/2013
Date:

3) Wei-Yi Hu
Name: Wei-Yi HU

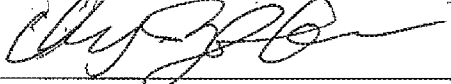
10/30 2013
Date:

4) Jui-Feng Kuan
Name: Jui-Feng KUAN

Oct. 29, 2013
Date:

5) Ching-Shun Yang
Name: Ching-Shun YANG

Oct. 29, 2013
Date:

6) 
Name: Yi-Kan CHENG

11.4.13
Date: